

# STP40NF10;ST;TO220;tranzystor; N-CHANNEL;50A;100V;150W;0.025R;Pbf



#### Dane techniczne:

Nazwa: STP40NF10 Typ tranzystora: unipolarny Kierunek przewodnictwa: N-MOSFET Prąd kolektora: 50A Napięcie kolektor-emiter: 100V Moc: 150W Montaż: przewlekany(THT) Obudowa: TO220 Producent: ST

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## STP40NF10

## N-channel 100 V, 0.025 Ω, 50 A TO-220 low gate charge STripFET™ II Power MOSFET

#### **Features**

Order code	V <sub>DSS</sub>	R <sub>DS(on)</sub> max.	I <sub>D</sub>
STP40NF10	IF10 100 V < 0.02		50 A

- Exceptional dv/dt capability
- Low gate charge
- 100% avalanche tested

### Application

Switching applications

### Description

This N-channel 100 V Power MOSFET is the latest development of STMicroelectronics unique "single feature size" strip-based process. The resulting transistor shows extremely high packing density for low on-resistance, rugged avalanche characteristics and less critical alignment steps allowing remarkable manufacturing reproducibility.

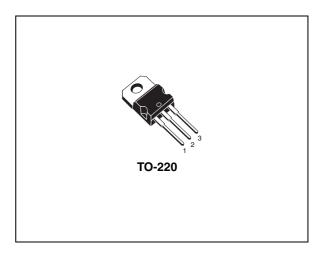
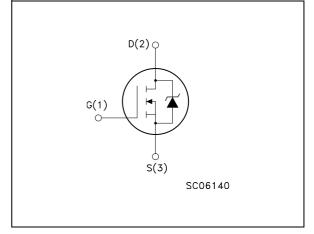


Figure 1. Internal schematic diagram



#### Table 1. Device summary

Order code	Marking	Package	Packaging
STP40NF10	P40NF10@	TO-220	Tube

## Contents

1	Electrical ratings	3
2	Electrical characteristics	4
	2.1 Electrical characteristics (curves)	6
3	Test circuit	8
4	Package mechanical data	9
5	Revision history1	1



#### 1

## **Electrical ratings**

Table 2. Absolute maximum rating	Table 2.	Absolute maximum rating
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Symbol	Parameter	Value	Unit	
V <sub>DS</sub>	Drain-source voltage (V <sub>GS</sub> = 0)	100	V	
V <sub>GS</sub>	Gate- source voltage	±20	V	
I <sub>D</sub> <sup>(1)</sup>	Drain current (continuous) at $T_{C} = 25 \ ^{\circ}C$	50	Α	
I <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 100 °C	35	Α	
I <sub>DM</sub> <sup>(2)</sup>	Drain current (pulsed)	200	Α	
P <sub>TOT</sub>	Total dissipation at T <sub>C</sub> = 25 °C	150	W	
	Derating factor	1	W/°C	
dv/dt <sup>(3)</sup>	Peak diode recovery voltage slope	27	V/ns	
E <sub>AS</sub> <sup>(4)</sup>	Single pulse avalanche energy	385	mJ	
T <sub>stg</sub>	Storage temperature - 55 to 175		°C	
Тj	Max. operating junction temperature	- 55 10 175		

1. Limited by wire bonding

2. Pulse width limited by safe operating area

3.  $I_{SD} \leq 50$  A, di/dt  $\leq 600$  A/µs,  $V_{DD} \leq V_{(BR)DSS}$ ,  $T_j \leq T_{JMAX.}$ 

4. Starting  $T_j$ = 25 °C,  $I_D$ = 50 A,  $V_{DD}$ =25 V

Symbol	Parameter	Value	Unit
R <sub>thj-case</sub>	Thermal resistance junction-case max	1	°C/W
R <sub>thj-a</sub>	Thermal resistance junction-ambient max	62.5	°C/W
Τ <sub>Ι</sub>	Maximum lead temperature for soldering purpose	300	°C



Symbol	Parameter	Test conditions	Min.	Тур.	Max	Unit
I <sub>SD</sub>	Source-drain current		-		80	А
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		320	А
V <sub>SD</sub> <sup>(2)</sup>	Forward on voltage	$I_{SD} = 50A, V_{GS} = 0$	-		1.5	V
t <sub>rr</sub> Q <sub>rr</sub> I <sub>RRM</sub>	Reverse recovery time Reverse recovery charge Reverse recovery current	$I_{SD} = 50A, V_{DD} = 25V$ di/dt = 100A/µs, T <sub>j</sub> = 150°C (see Figure 16)	-	80 250 6.4		ns nC A

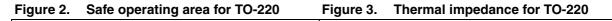
#### Table 7.Source drain diode

1. Pulse width limited by safe operating area.

2. Pulsed: Pulse duration = 300  $\mu$ s, duty cycle 1.5%



### 2.1 Electrical characteristics (curves)

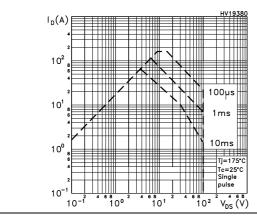


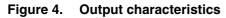
κ

10

10<sup>-2</sup>

 $\delta = 0.5$ 





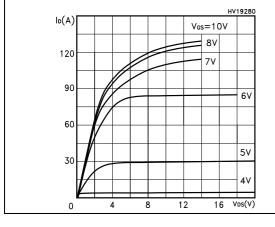


Figure 6. Transconductance



10-4

1111

0.05 0.02

10-3

10-2

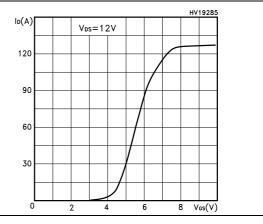
0.02

SINGLE PULSE

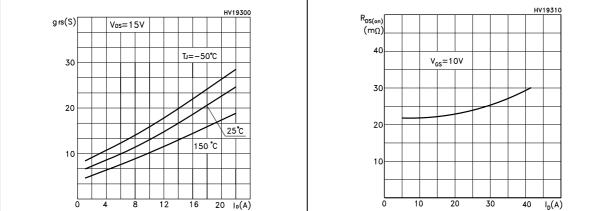
 $Z_{th} = k R_{thJ-c}$ 

10<sup>-1</sup> † P (s)

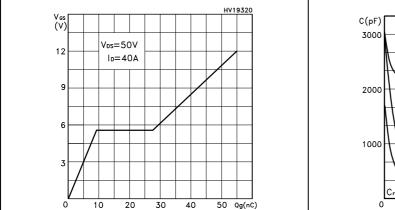
 $\delta=\,{\rm t_p}\,/\tau$ 











#### Figure 8. Gate charge vs. gate-source voltage Figure 9. Capacitance variations

Figure 10. Normalized gate threshold voltage vs. temperature

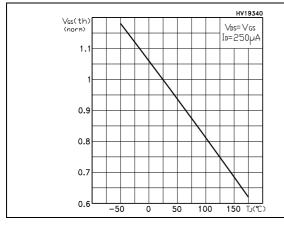


Figure 12. Source-drain diode forward characteristics

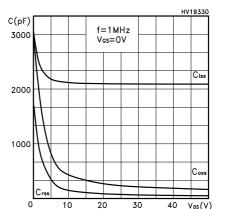


Figure 11. Normalized on resistance vs. temperature

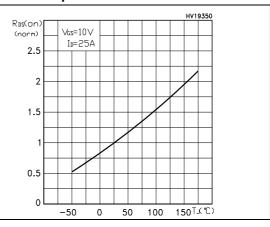
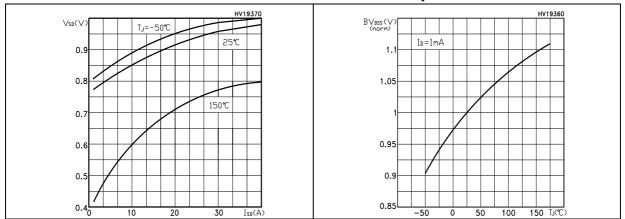


Figure 13. Normalized breakdown voltage vs. Tj





## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: www.st.com. ECOPACK is an ST trademark.



## 5 Revision history

#### Table 8.Document revision history

Date	Revision	Changes
16-Dec-2004	1	First version.
17-Aug-2006	2	The document has been reformatted.
31-Jan-2007	3	Typo mistake on <i>Table 2</i> .
19-Sep-2007	4	Added DPAK.
10-Nov-2010	5	Removed DPAK.



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